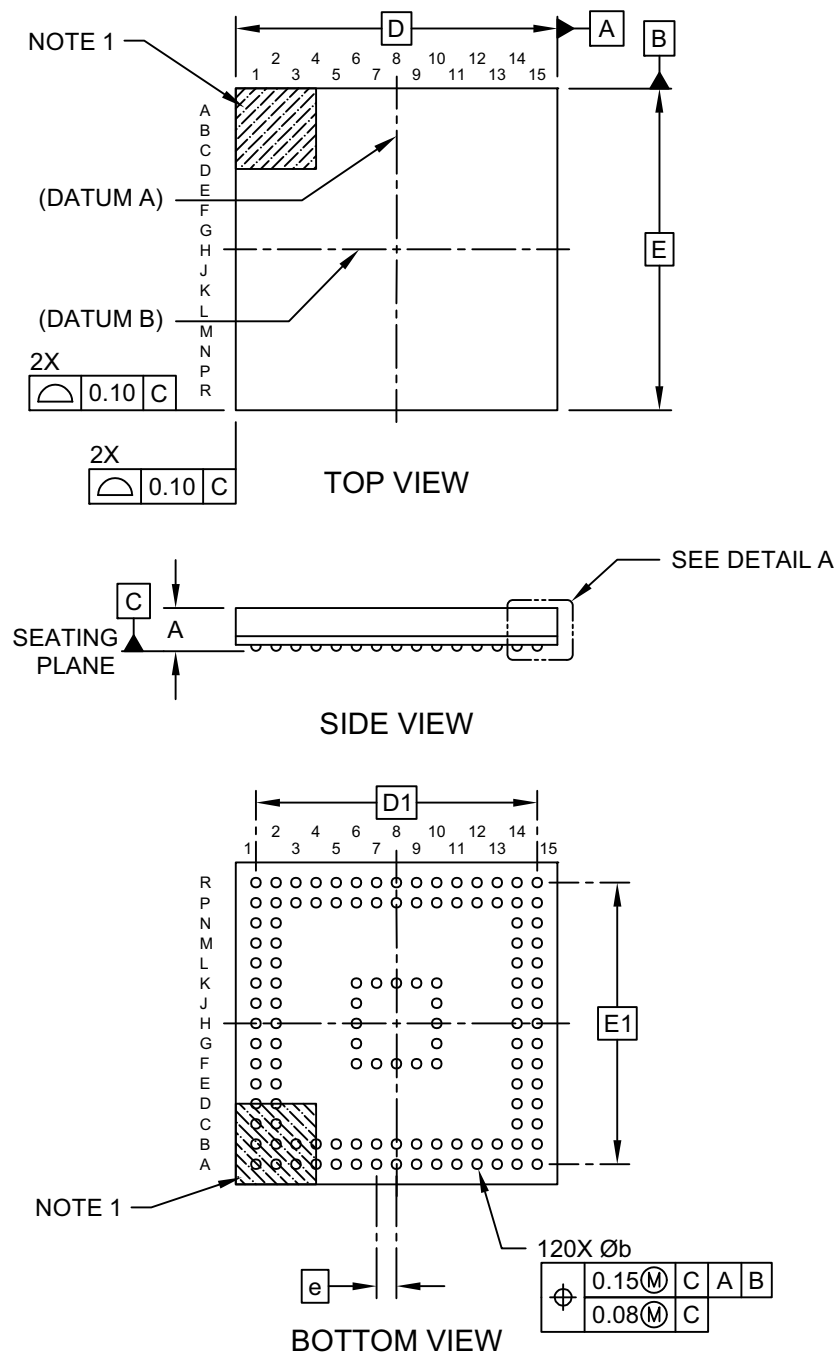


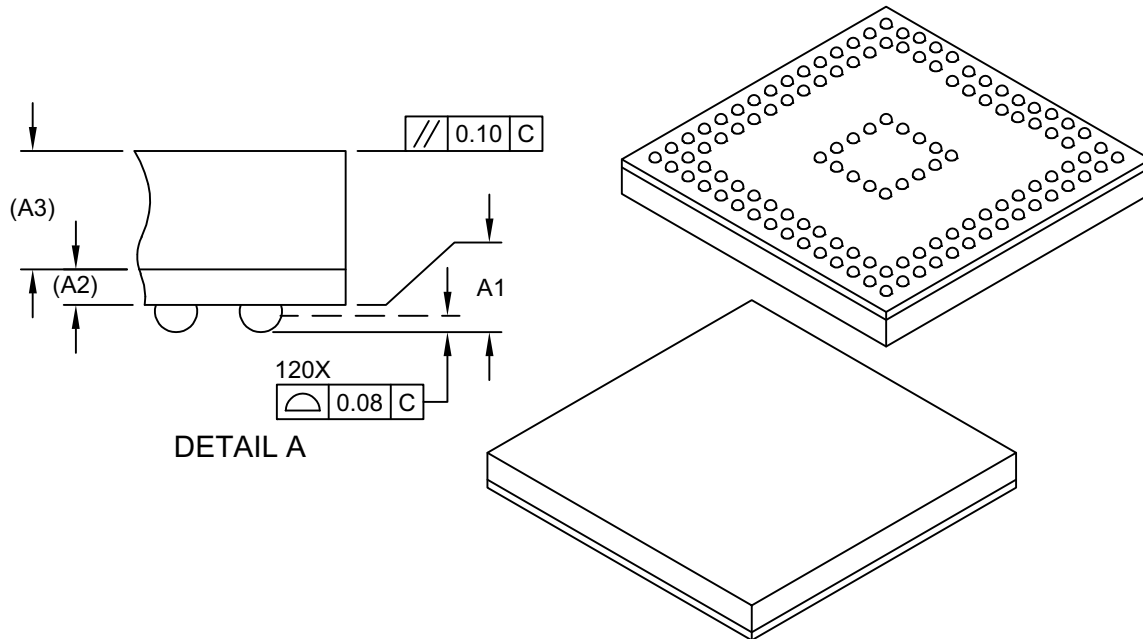
120-Ball Thin Fine Pitch Ball Grid Array Package (HEB) - 8x8 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



120-Ball Thin Fine Pitch Ball Grid Array Package (HEB) - 8x8 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



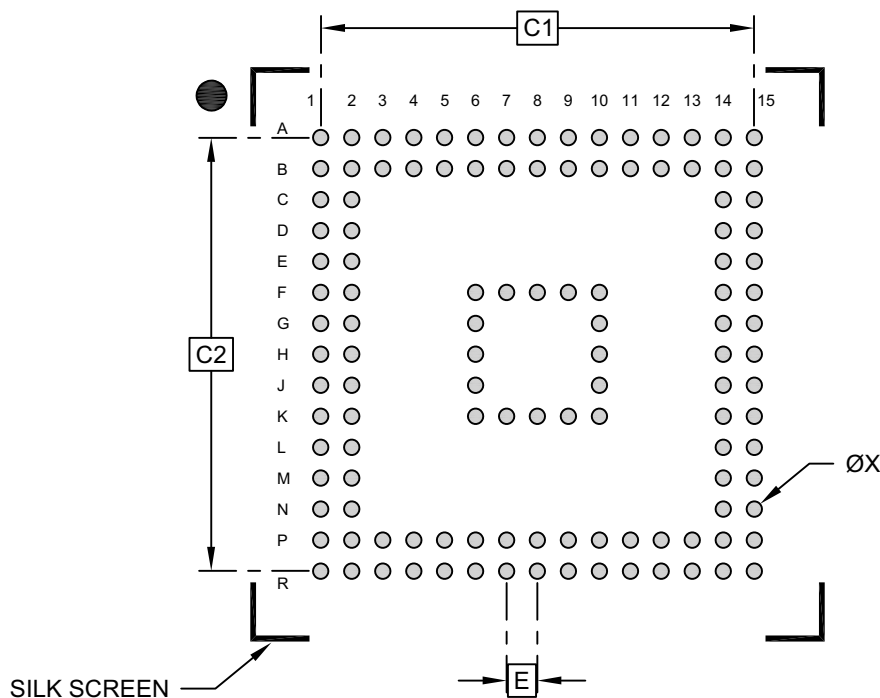
Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	120		
Pitch	e	0.50 BSC		
Overall Height	A	-	-	1.20
Standoff	A1	0.11	-	0.21
Substrate Thickness	A2	0.21 REF		
Mold Cap Thickness	A3	0.70 REF		
Overall Length	D	8.00 BSC		
Overall Ball Pitch	D1	7.00 BSC		
Overall Width	E	8.00 BSC		
Exposed Pad Width	E1	7.00 BSC		
Terminal Width	b	0.20	-	0.30

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

120-Ball Thin Fine Pitch Ball Grid Array Package (HEB) - 8x8 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1	7.00 BSC		
Contact Pad Spacing	C2	7.00 BSC		
Contact Pad Width (X20)	X		0.25	

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-23465-HEB Rev C